

ABSTRACT

A semiconductor package includes a wiring structure, a first bump, and a semiconductor chip. The wiring structure includes a first electrode and has a first surface and a second surface that faces away
5 from the first surface. The second surface of the wiring structure includes a recessed area that overlaps the first electrode. The first bump includes a first conductive pillar on the first surface of the wiring structure and a first solder layer on the first conductive pillar. The first bump contacts the first electrode. The first electrode
10 includes a first section and a second section. The first section of the first electrode is disposed between the first surface of the wiring structure and the second surface of the wiring structure. The second section of the first electrode has a lower surface that is included in the first surface of the wiring structure. The horizontal width of the first
15 conductive pillar is less than the horizontal width of the first electrode. A semiconductor chip is disposed above the second surface of the wiring structure.

FIG. 1